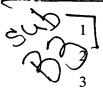
## WHAT IS CLAIMED IS:



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1. A package for mounting at least one integrated circuit die, the package comprising at least one one-time programmable element having a first and a second end separated by a programmable link, wherein the first end of the one-time programmable element is coupled to a power supply voltage node in the package.

- 1 2. The package as recited in claim 1 wherein the programmable element 2 is one of a fuse and an artifuse.
- 1 3. The package as recited in claim 2 wherein the package is a
  multilayered package and the programmable element is formed of a metalization
  pattern located on a surface of the package.
  - 4. The package as recited in claim 2 wherein the package is a multilayered package and the programmable element is located on a layer other than the surface of the package.
  - 5. The package as recited in claim 2 wherein the programmable element is covered by a protective layer.
  - 6. The package as recited in claim 2 wherein the programmable element is not covered by a protective layer.
  - The package as recited in claim 2 wherein the second end of the programmable element is coupled to at least one of an external package connection and a package contact that connects to an input terminal of the integrated circuit die, after mounting of the integrated circuit die.
- 1 (8.) The package as recited in claim 2 wherein the programmable element 2 is coupled to the power supply terminal through a resistive element.
- The package as recited in claim 2 wherein the second end of the programmable element is coupled to an external package connection and to an



- 3 internal package node that couples to an input terminal of the integrated circuit die
- 4 when the integrated circuit die is mounted.
- 10. The package as recited in claim 2 wherein the programmable element 1 2 is programmable using a laser.
- 1 11. The package as recited in claim 2 wherein the programmable element 2 is programmable using an electrical current.

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The package as recited in claim 2 further comprising another programmable element coupled between the second end of the programmable element and an external package connection.

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The package as testited in claim 1 further comprising a second one-13. time programmable element oupled in parallel with the one time programmable element and wherein the one one-time programmable element is a fuse and the second one-time programmable element is an antifuse.

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The package as recited in claim 2 wherein the package includes 14. at least one pair of programmable elements, the one pair including the one one-time programmable element and a second one-time programmable element, the second one-time programmable element having a first and second end, the first end of the second one-time programmable element coupled to a second power supply voltage node and the second end of the second one-time programmable element being coupled through an internal package node to the second end of the first -onetime programmable element.

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The package as recited in claim 14 wherein the internal package node is coupled to at least one of an external pagkage connection and an input terminal of the integrated circuit die, after mounting of the integrated circuit die.

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16. The package as recked in claim 14 further comprising a first resistive element coupled between the internal package node and the power supply node and a 5

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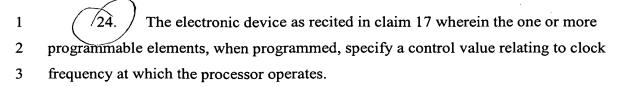
second resistive element coupled between the internal package node and the second power supply node.

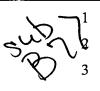
1 17. An electronic device comprising:
2 a package including one or more one-time programmable elements having a first and a second end separated by a programmable link, wherein the first end of the one one-time programmable element is coupled to a

power supply voltage node in the package and a second end of the

- programmable link is coupled to an internal package node; and at least one integrated circuit die mounted in the package.
  - 18. The electronic device as recited in claim 17 wherein the one or more programmable elements specify one or more operating parameters relating to the electronic device.
  - The electronic device as recited in claim 18 wherein the integrated circuit die includes a processor and the one or more operating parameters specify an operating voltage of at least a portion of the processor.
    - 20.) The electronic device as recited in claim 17 wherein the internal package node is coupled to at least one of an external package connection and the integrated circuit die.
- 1 21. The electronic device as recited in claim 20 wherein the internal package node couples to an external package connection through another programmable element.
  - The electronic device as recited in claim 17 wherein the package is a multilayered package and the programmable element is located on a surface of the package.
    - 23. The electronic device as recited in claim 17 wherein the package is a multi-layered package and the programmable element is located on a layer other than the surface of the package.

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- The electronic device as recited in claim 17 wherein a state of the programmable element specifies use of error correction code (ECC) for a cache memory on the processor.
- 26. The electronic device as recited in claim 17 wherein the one one-time programmable element is part of a one-time programmable element pair, the programmable element pair including a second one-time programmable element in addition to the one one-time programmable element, the second programmable element having a first end coupled to the internal package node and a second end coupled to a second power supply voltage.
- 27. The electronic device as recorded in claim 26 further comprising a first resistive element coupled respectively between the internal package node and the first power supply node and a second resistive element coupled between the internal package node and the second power supply node, thereby providing a voltage divider when the first power supply node is electrically coupled to the second power supply node through the programmable element pair.
- 28. A method for setting a parameter value for an integrated circuit, comprising:
  selectively programming one or more one-time programmable elements
- selectively programming one or more one-time programmable elements

  located on an integrated circuit package, thereby selectively coupling
  an internal package node to a supply voltage node.
  - 29. The method as recited in claim 28 wherein the one-time programmable elements are one of a fuse and an antifuse.

I	30.	The method as recited in claim 29 wherein the internal package node
2	couples to at	least one of an external package connection and an input contact of an
3	integrated circuit die.	
	0.1	
1	31.	The method as recited in claim 29 wherein the specifies an operating
2	voltage for at	least a portion of the integrated circuit.
1	32.	The method as recited in claim 29 wherein an integrated circuit die is
2	mounted on the package when the one or more one-time programmable elements are	
3	being selectiv	rely programmed.
1	33.	A method comprising.
2	selecti	ively programming a first programmable element of a programmable
3		element pair located on an integrated circuit package to selectively
4		couple an internal node to a first power supply voltage; and
5	selecti	vely programming a second programmable element of the
6		programmable element pair to selectively couple the internal node to a
7		second power supply voltage.
1	34.	The method as recited in claim 33 wherein the internal node is coupled
2	to at least one of an external package connection and an input terminal of an	
3	integrated circuit die mounted in the integrated circuit package.	
1	35.	The method as recited in claim 33 wherein the first power supply
2	voltage is ground (Vss).	
1	36.	The method as recited in claim 33 wherein the second power supply
2	voltage is Vcc.	
1	37.	An apparatus comprising:

means for specifying a parameter value for the apparatus.

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a semiconductor package; and



omey Docket No.: 1001-0087

- 1 38. The apparatus as recited in claim 37 further comprising a processor
- 2 mounted in the semiconductor package.